PATENT
Atty. Dkt. No. APPM/008241/PPC/ECP/CKIM

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Sun et al.
Serial No.: 10/616,097
Confirmation No.: 1645
Filed: July 8, 2003
For: Multiple-Step Electrodeposition Process for Direct Copper Plating on Barrier Metals

Group Art Unit: 1753
Examiner: Edna Wong

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CERTIFICATE OF FACSIMILE TRANSMISSION UNDER 37 CFR 1.8

I hereby certify that this correspondence and the documents referred to as attached therein are being facsimile transmitted to the U.S. Patent and Trademark Office to the fax number indicated by the Examiner, namely, fax number 571.273.8300 to the attention of the named Examiner, on the date below.

December 2, 2005
Date
Signature

MAIL STOP AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

RESPONSE TO FINAL OFFICE ACTION DATED OCTOBER 4, 2005

In response to the Final Office Action dated October 4, 2005, having a shortened statutory period for response set to expire on January 4, 2006, please enter this response and reconsider the claims pending in the application for reasons discussed below. Although the Applicant believes that no additional fees are due in connection with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/APPM/008241/KMT, for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

Amendments to the Claims begin on page 2 of this paper. **Remarks** begin on page 8 of this paper.